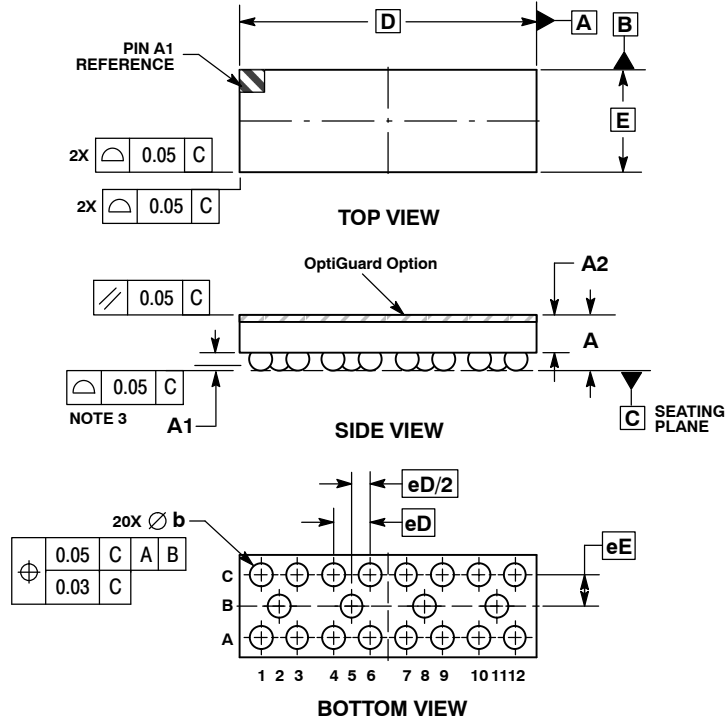




SCALE 4:1

WLCSP20, 3.27x1.13  
CASE 567BW  
ISSUE O

DATE 26 JUL 2010

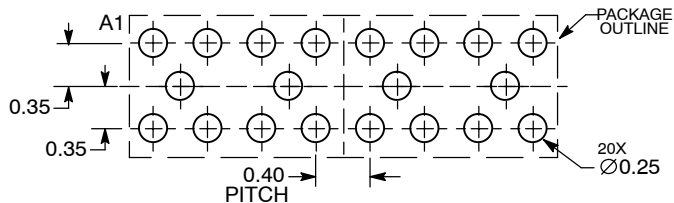


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

| DIM | MILLIMETERS |      |
|-----|-------------|------|
|     | MIN         | MAX  |
| A   | 0.54        | 0.69 |
| A1  | 0.17        | 0.24 |
| A2  | 0.42        | REF  |
| b   | 0.24        | 0.29 |
| D   | 3.27        | BSC  |
| E   | 1.13        | BSC  |
| eD  | 0.400       | BSC  |
| eE  | 0.347       | BSC  |

RECOMMENDED  
SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

|                  |                    |   |
|------------------|--------------------|---|
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| DESCRIPTION:     | WLCSP20, 3.27x1.13 | PAGE 1 OF 1   |

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